



# Product Change Notification

**Change Notification #:** 115927 - 00  
**Change Title:** Select Intel® Optane™ Memory Series, PCN 115927-00, Label, Label Update  
**Date of Publication:** November 27, 2017

**Key Characteristics of the Change:**  
 Label

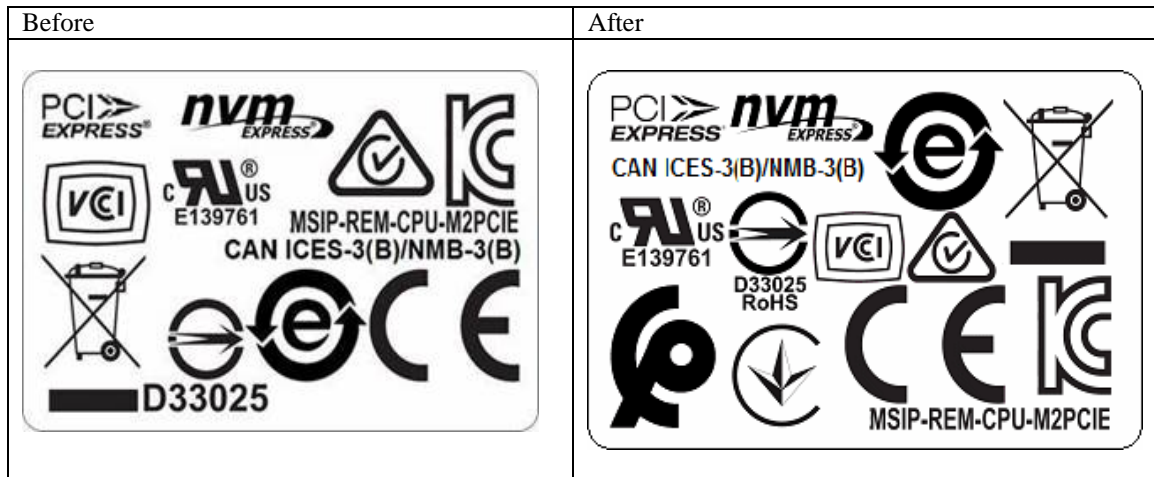
**Forecasted Key Milestones:**

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Dec 08, 2017
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**Description of Change to the Customer:**

The Intel® Optane™ Memory Series SKUs listed in the Products Affected Table below will have the following change.

- The thermal regulatory label will be updated to include BSMI ROHS for Morocco and Ukraine. See pictures below for before and after images.



**Customer Impact of Change and Recommended Action:**

There is no change to the Form, Fit, or Function of the product. The change is only to the labels used in packaging.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

## Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#	TA	SA
Intel® Optane™ Memory Series (16GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Generic Single Pack	MEMPEK1W016GA01	953340	J45694-101	J45811-102
Intel® Optane™ Memory Series (32GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Generic Single Pack	MEMPEK1W032GA01	953341	J45695-101	J45812-102
Intel® Optane™ Memory Series (16GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Retail Box 10pk	MEMPEK1W016GAXT	957790	J57060-101	J45811-102
Intel® Optane™ Memory Series (32GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Retail Box 10pk	MEMPEK1W032GAXT	957793	J57061-101	J45812-102
Intel® Optane™ Memory Series (16GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Generic 100pk	MEMPEK1W016GA	957794	J57062-101	J45811-102
Intel® Optane™ Memory Series (32GB, M.2 80mm PCIe 3.0, 20nm, 3D Xpoint) Generic 100pk	MEMPEK1W032GA	957795	J57063-101	J45812-102

## PCN Revision History:

**Date of Revision:**

November 27, 2017

**Revision Number:**

00

**Reason:**

Originally Published PCN



# Product Change Notification

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**Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.**

**Americas Contact:** [asmo.pcn@intel.com](mailto:asmo.pcn@intel.com)

**Asia Pacific/PRC Contact:** [apagccb@intel.com](mailto:apagccb@intel.com)

**Europe Email:** [eccb@intel.com](mailto:eccb@intel.com)

**Japan Email:** [jccb.ijkk@intel.com](mailto:jccb.ijkk@intel.com)

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